

Features

- · Trench MV MOSFET Technology
- ESD Protected Up To 2KV (HBM)
- Operated At Low Logic Level Gate Drive
- · Moisture Sensitivity Level 1
- Halogen Free. "Green" Device (Note1)
- Epoxy Meets UL 94 V-0 Flammability Rating
- · Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)

P-Channel MOSFET

Maximum Ratings

- Operating Junction Temperature Range: -55°C to +150°C
- Storage Temperature Range: -55°C to +150°C
- Thermal Resistance: 461°C/W Junction to Ambient(Note2)

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Parameter		Symbol	Rating	Unit	
Drain -source Voltage		V_{DS}	-60	V	
Gate -Source Voltage		V_{GS}	±20	V	
Continuous Drain Current	T _A =25°C	. I _D	-0.26	A	
	T _A =100°C		-0.16		
Plused Drain Current (Note3)		I _{DM}	-1.04	Α	
Power Dissipation ^(Note4)		P _D	0.27	W	

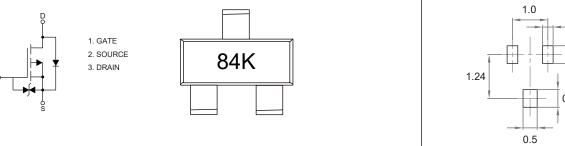
Note:

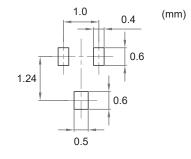
- 1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 2. The value of $R_{\theta JA}$ is measured with the device mounted on 1in^2 FR-4 board with 2oz. Copper, in a still air environment with T_A =25°C.
- 3. Repetitive rating; pulse width limited by max. junction temperature.
- 4. P_D is based on max. junction temperature, using junction-ambient thermal resistance.

SOT-523

DIMENSIONS					
DIM INC		HES	HES MM		NOTE
DIIVI	MIN	MAX	MIN	MAX	NOTE
Α	0.059	0.067	1.50	1.70	
В	0.030	0.033	0.75	0.85	
С	0.057	0.069	1.45	1.75	
D	0.020		0.50		TYP.
E	0.035	0.043	0.90	1.10	
G	0.000	0.004	0.00	0.10	
Н	0.024	0.031	0.60	0.80	
J	0.004	0.008	0.10	0.20	
K	0.006	0.014	0.15	0.35	

Internal Structure and Marking Code Suggested Solder Pad Layout







Electrical Characteristics @ 25°C (Unless Otherwise Specified)

Parameter	Symbol	Test conditions	Min	Тур	Max	Unit	
Static Characteristics							
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =-250μA	-60			V	
Gate-Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =-250μA	-1.0	-1.5	-2.0	V	
Gate-Body Leakage Current	I _{GSS}	V _{GS} =± 20V, V _{DS} =0V			±10	μA	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-48V, V _{GS} =0V			-1	μA	
Drain-Source On-Resistance	D	V _{GS} =-10V, I _D =-0.2A		2.0	6	Ω	
	R _{DS(on)}	V _{GS} =-4.5V, I _D =-0.1A		2.3	7		
Forward Transconductance	g _{FS}	V _{DS} =-10V, I _D =-0.1A		0.37		S	
Gate Resistance	R _g	f=1 MHz, Open drain		1270		Ω	
Diode Characteristics				1	I.		
Continuous Body Diode Current	Is				-0.26	Α	
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =-0.2A			-1.3	V	
Reverse Recovery Time	t _{rr}	1 = 0.24 dl /dt=4004/vo		13		ns	
Reverse Recovery Charge	Q _{rr}	I _F =-0.3A, dI _F /dt=100A/μs		5.8		nC	
Dynamic Characteristics			'		<u>I</u>		
Input Capacitance	C _{iss}	V_{DS} =-25V,V _{GS} =0V,f=1MHz 6		37		pF	
Output Capacitance	C _{oss}			6			
Reverse Transfer Capacitance	C _{rss}			3.8		-	
Total Gate Charge	Qg			2.2			
Gate-Source Charge	Q _{gs}	V _{DS} =-25V,V _{GS} =-10V,I _D =-0.3A		0.4		nC	
Gate-Drain Charge	Q_{gd}			0.2			
Turn-On Delay Time	t _{d(on)}			8.3			
Turn-On Rise Time	t _r	V _{DD} =-25V,V _{GS} =-10V,		4			
Turn-Off Delay Time	t _{d(off)}	$R_{G}=3.9\Omega, I_{D}=-0.3A$		39		ns	
Turn-Off Fall Time	t _f			20		1	



Curve Characteristics

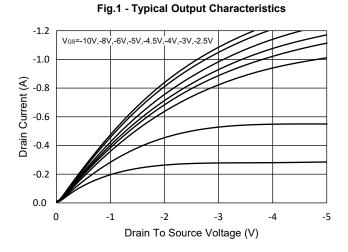


Fig.2 - Transfer Characteristic

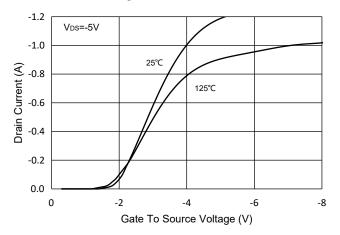


Fig.3 - $R_{DS(ON)}$ - V_{GS} 10.0 I_D=-0.1A 9.0 Drain-Source On-Resistance (Ω) 8.0 7.0 6.0 5.0 4.0 125℃ 3.0 2.0 25℃ 1.0 0 0 -2 -8 -4 -10 Gate To Source Voltage (V)

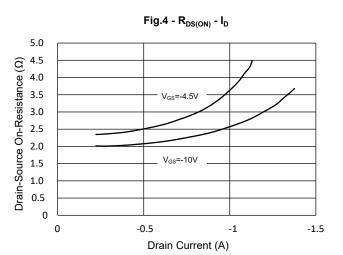


Fig.5 - Capacitance Characteristics

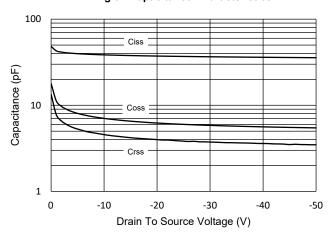
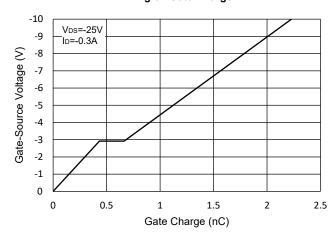
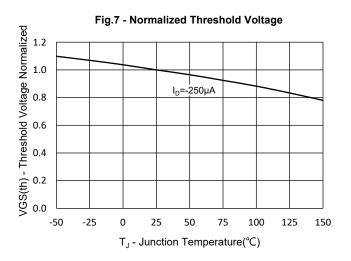


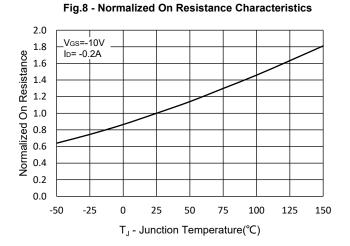
Fig.6 - Gate Charge

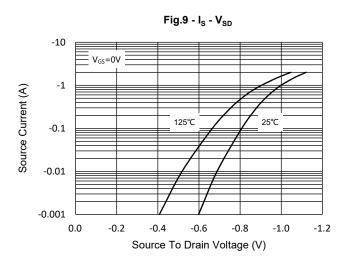


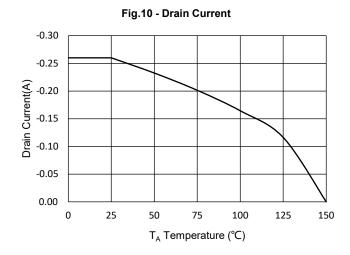


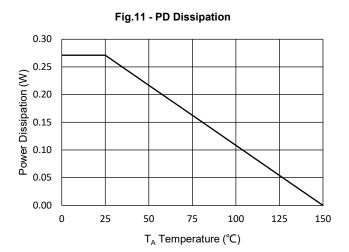
Curve Characteristics













Curve Characteristics

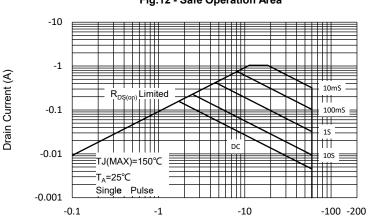
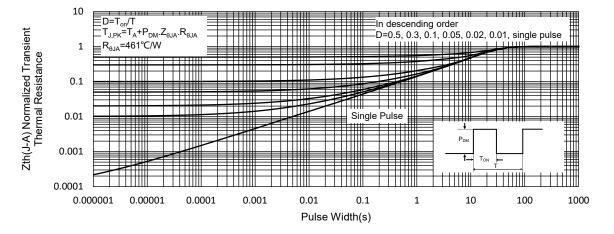


Fig.12 - Safe Operation Area

Drain-Source Voltage (V)







Ordering Information

Device	Packing
Part Number-TP	Tape&Reel:3Kpcs/Reel

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